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| Orderable: SideGig-OPA1632EVM | Designed for: Public Release | Mod. Date: 12/4/2017 |
| TID #: TIDA-01359 | Project Title: SideGig-OPA1632EVM | |
| Number: TIDA-01359 | Rev: A | Sheet Title: SideGig-OPA1632EVM Circuit |
| SVN Rev: Version control disabled | Assembly Variant: 001 | Sheet: 1 of 2 |
| Drawn By: Wayne Comeaux | File: TIDA-01359A.SchDoc | Size: B |
| Engineer: Wayne Comeaux | Contact: http://www.ti.com/support | |

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H1 PMSSS 440 0025 PH
 H2 PMSSS 440 0025 PH
 H3 PMSSS 440 0025 PH
 H4 PMSSS 440 0025 PH

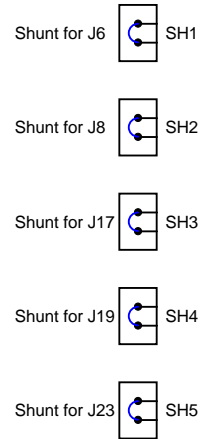
H5 3483
 H6 3483
 H7 3483
 H8 3483

DNP FID1
 DNP FID2
 DNP FID3
 DNP FID4
 DNP FID5
 DNP FID6

PCB Number: TIDA-01359
 PCB Rev: A

PCB LOGO
 Texas Instruments
 PCB LOGO
 Pb-Free Symbol
 PCB LOGO
 FCC disclaimer

Note: Board is shipped to customer with all 5 shunts connecting from header pin 2 to pin 3



Label Table

| Variant | Label Text |
|---------|--------------------|
| 001 | SideGig-OPA1632EVM |
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LBL1
 PCB Label
 Size: 0.65" x 0.20"

ZZ1
 Label Assembly Note
 This Assembly Note is for PCB labels only

ZZ2
 Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
 Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
 Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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|-----------------------------------|------------------------------------|--|
| Orderable: SideGig-OPA1632EVM | Designed for: Public Release | Mod. Date: 12/1/2017 |
| TID #: TIDA-01359 | Project Title: SideGig-OPA1632EVM | |
| Number: TIDA-01359 | Rev: A | Sheet Title: SideGig-OPA1632EVM Hardware |
| SVN Rev: Version control disabled | Assembly Variant: 001 | Sheet: 2 of 2 |
| Drawn By: Wayne Comeaux | File: TIDA-01359A_Hardware.SchDoc | Size: B |
| Engineer: Wayne Comeaux | Contact: http://www.ti.com/support | |

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